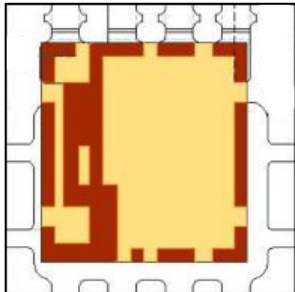
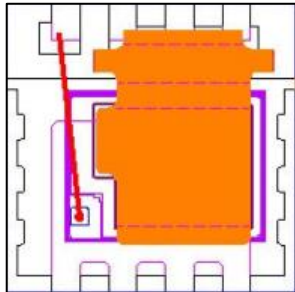
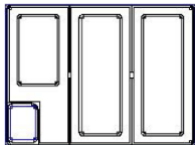
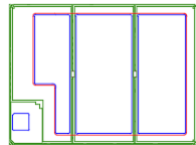
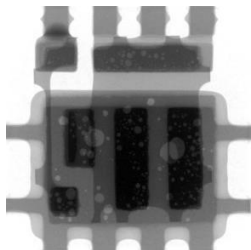
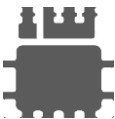
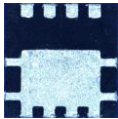
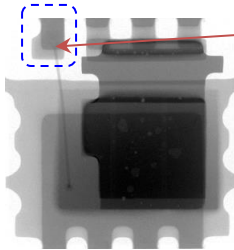
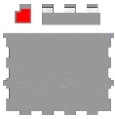




Title of Change:	PQFN_33CLP Metal Clip with Cu Gate Wire Conversion	
Proposed first ship date:	10 August 2018 or earlier upon customer approval	
Contact information:	Contact your local ON Semiconductor Sales Office or <Joseph.Mendoza@onsemi.com>	
Samples:	Contact your local ON Semiconductor Sales Office or <PCN.Samples@onsemi.com>	
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <KarenMae.Taping@onsemi.com>	
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.	
Change Part Identification:	Affected products will be identified with date code	
Change category:	☐ Wafer Fab Change ☒ Assembly Change ☐ Test Change ☐ Other _____	
Change Sub-Category(s):	☐ Manufacturing Site Change/Addition ☒ Material Change ☐ Datasheet/Product Doc change ☒ Manufacturing Process Change ☐ Product specific change ☐ Shipping/Packaging/Marking ☐ Other: _____	
Sites Affected:	ON Semiconductor Sites: ON Cebu, Philippines	External Foundry/Subcon Sites: None
Description and Purpose: Conversion of PQFN_33CLP from using Pre-Molded Clip to Metal Clip with Cu Gate wire to improve Gate leadpost interconnection. The conversion will entail the following assembly process and package dimension changes: 1. Addition of Process steps, i.e., Die Top Print prior Clip bond, Flux Clean prior Wirebond, Wirebond for Gate wire, and Plasma Clean prior Mold. 2. Change in Clip bonding process technology from Pick and Place of Saw Singulated Pre-molded Clip to Pick and Place of Punch Singulated Metal Clip. 3. Removal of exposed tie bars at bottom part of package.		
Material to be changed	Before Change Description	After Change Description
Clipframe	Pre-molded Clip (0.254mm thick) 	Bare Metal Clip (0.508mm thick) with 2mil Cu Gate Wire 



Material to be changed	Before Change Description	After Change Description
Die Solderable Top Metal (STM)	Both Gate and Source pads have TiNiAg STM  Notes: 1. "R" on die item name means both Gate and Source pads have TiNiAg STM.	Only Source pad has TiNiAg STM. No TiNiAg STM on Gate pad for Cu wire bonding purposes  Notes: 1. Blue lines are for polyimide opening. 2. Red lines are for TiNiAg STM outline with 15um overlap on PI. 3. "M" on die item name means no TiNiAg STM on Gate pad.
Leadframe	Leadframe without plating on Gate leadpost Die Attach Pad Dimensions: 2.667x2.032mm Source Leadpost Pad Dimensions: 1.62x0.47mm Gate Leadpost Pad Dimensions: 0.58x0.47mm    Top View Bottom View (Package Outline)	Leadframe with Spot Ag plating on Gate leadpost for Cu wire bonding purposes Die Attach Pad Dimensions: 2.898x2.261mm Source Leadpost Pad Dimensions: 1.705x0.35mm Gate Leadpost Pad Dimensions: 0.46x0.35mm    Top View Bottom View (Package Outline) Ag plated Gate leadpost

**Reliability Data Summary:**QV DEVICE NAME: FDMC7570SRMS: F43951PACKAGE: PQFN_33CLP

Test	Specification	Condition	Interval	Lot A	Lot B	Lot C
IOL-PC	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2 min	Post PC Electrical	0/80	0/80	0/80
			7,500 cyc	0/80	0/80	0/80
			15,000 cyc	0/80	0/80	0/80
TC-PC	JESD22-A104	Temp = -65°C to +150°C	Post PC Electrical	0/80	0/80	0/80
			100 cyc	0/80	0/80	0/80
			500 cyc	0/80	0/80	0/80
			1,000 cyc	0/77	0/77	0/77
HAST-PC	JESD22-A110	Temp = +130°C, RH = 85%, p = 18.8psig, bias	Post PC Electrical	0/80	0/80	0/80
			96 hrs	0/80	0/80	0/80
UHA-PC	JESD22-A118	Temp = +130°C, RH = 85%, p = 18.8psig, unbiased	Post PC Electrical	0/80	0/80	0/80
			96 hrs	0/80	0/80	0/80

Electrical Characteristic Summary:

Electrical characteristics are not impacted.

List of Affected Standard Parts:

Part Number	Qualification Vehicle
FDMC7570S	FDMC7570S
FDMC7660S	